

WHAT IS CLAIMED IS:

1. A wafer processing method for use with a wafer processing apparatus comprising a liquid cooling jacket with a built-in coolant liquid circulation path and a ceramic plate as attached onto the liquid cooling jacket and having therein a heater and an electrode for an electrostatic chuck, the method enabling performance of wafer processing while letting a wafer be mounted on the ceramic plate by a wafer transport, the method comprising the steps of:

causing the wafer transport to transport the wafer onto the ceramic plate;

pre-heating the wafer while the wafer is held on the ceramic plate for a predetermined length of time; and

mounting the preheated wafer on the ceramic plate.

2. A wafer processing method for use with a wafer processing apparatus comprising a liquid cooling jacket with a built-in coolant liquid circulation path and a ceramic plate as attached onto the liquid cooling jacket and having therein a heater and an electrode for an electrostatic chuck, the method enabling performance of wafer processing while letting a wafer be mounted on the ceramic plate by a wafer transport, the method comprising the steps of:

causing the wafer transport to transport the wafer onto the ceramic plate;

pre-heating the wafer while the wafer is on the ceramic plate for a predetermined length of time;

mounting the preheated wafer on the ceramic plate;

transporting the processed wafer toward a buffer chamber for effectuation of pre-cooling; and
unloading the wafer thus precooled.